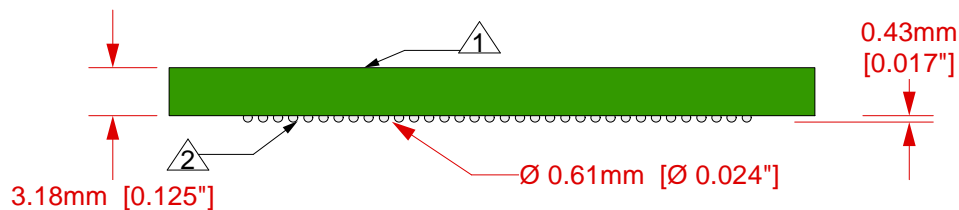


Top View




Side View

- 1 Substrate: 3.18mm ±0.18mm [0.125" ±0.007"]
FR4/G10 or equivalent high temp material. 17µm
[1/2 oz.] Cu clad. SnPb plating.
- 2 Solder ball: Eutectic Sn63Pb37

Description: BGA Surface Mount Adaptor

1156 position surface mount land pattern to solder balls. To be used with GHz sockets.

Tolerances: diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SF-BGA1156A-B-05 Drawing		Status: Released	Scale: 2:1	Rev: A
 <p>© 2008 IRONWOOD ELECTRONICS, INC. Tele: (800) 404-0204 www.ironwoodelectronics.com</p>	Drawing: E Smolentseva		Date: 11/21/08	
	File: SF-BGA1156A-B-05 Dwg		Modified:	